

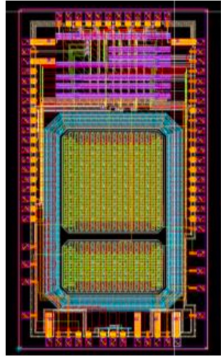


40 picoseconds time resolution analysis from test beam of monolithic pixel sensors.

Théo Moretti on behalf of the MONOLITH team

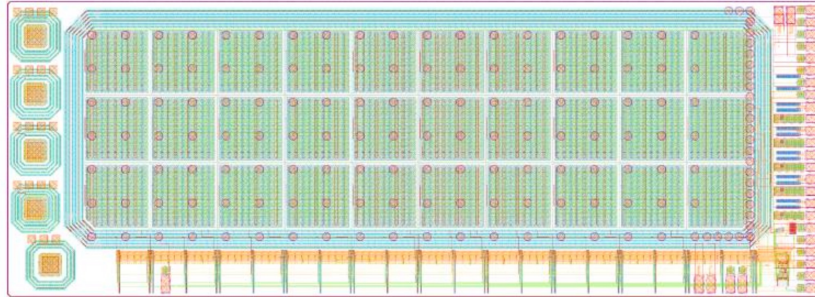
10th Beam Telescopes and Test Beams Workshop – Lecce

2016



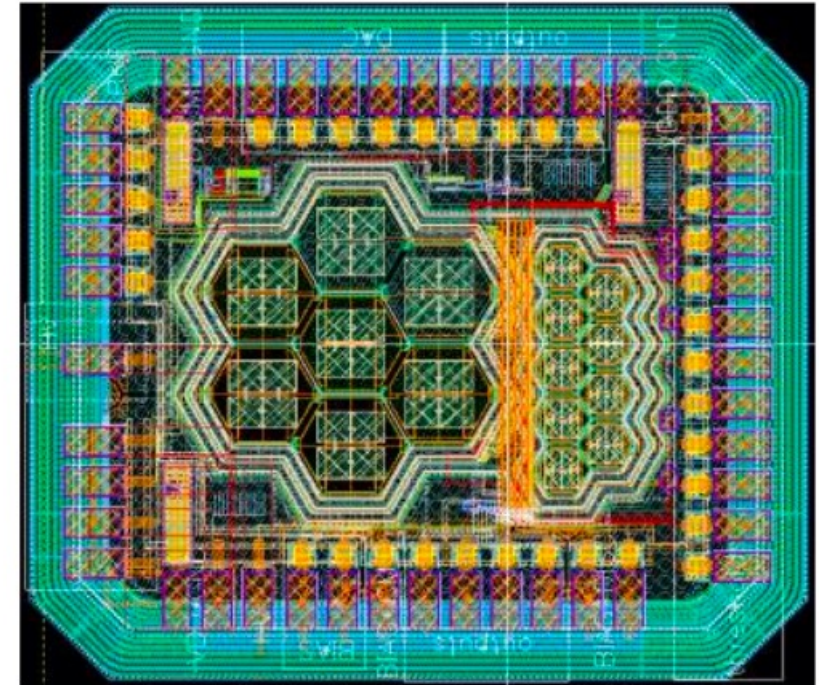
200 ps

2017



100 ps

2018



50 ps time resolution

2018 prototype:

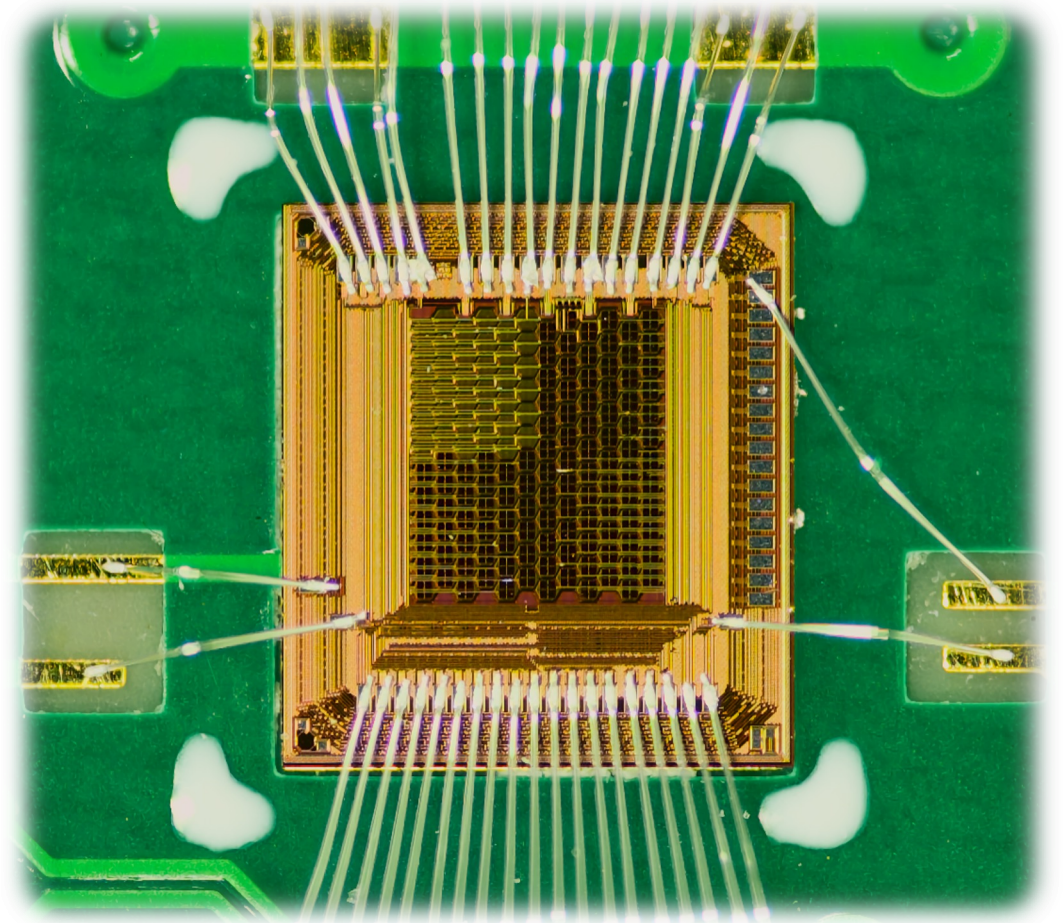
- Hexagonal pixels: 65 μm side (100 μm pitch)
- Discriminator output
- High discrimination threshold
- Time Over Threshold (TOT) used for Time Walk Correction

Ref: <https://iopscience.iop.org/article/10.1088/1748-0221/14/02/P02009>

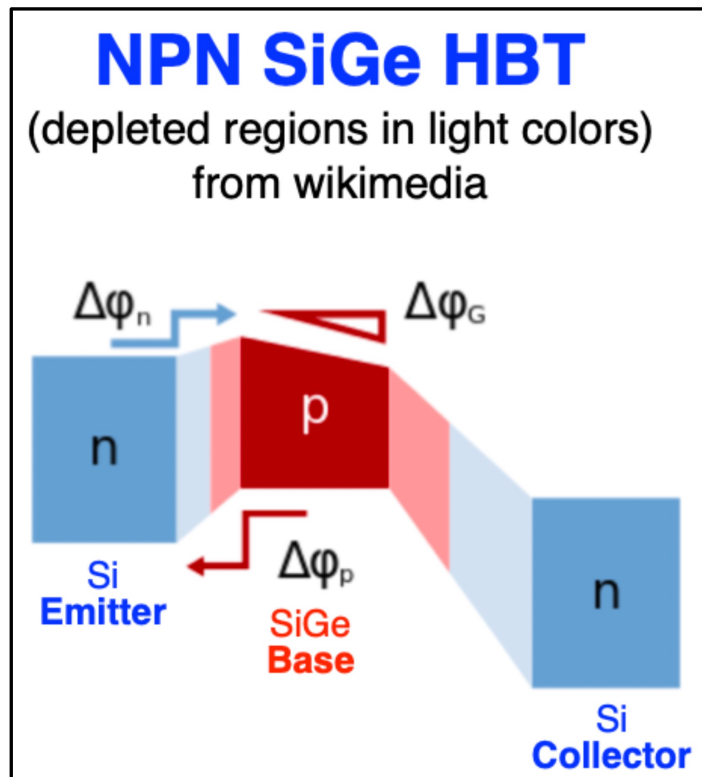
Ref: <https://iopscience.iop.org/article/10.1088/1748-0221/13/04/P04015>

Ref: <https://iopscience.iop.org/article/10.1088/1748-0221/14/11/P11008>

- **Monolithic SiGe BiCMOS pixel sensor**
 - SiGe BiCMOS technology
 - Sensor characteristics
- **Test Beam measurements**
 - The FEI4 telescope and experimental setup
 - Efficiency
 - Correcting for time walk
 - Time resolution
- **Summary and Outlook**



Recipe for timing: **ultra-fast**, **low noise** and **high gain** amplifier



SiGe Hetero Bipolar Transistor (HBT) = Bipolar Junction Transistor (BJT) with Germanium in base material:

- **Reduced base resistance R_b**

Grading of Germanium doping in base:

- **Higher current gain β**
- **Charge transport via drift**

Reduced Equivalent Noise Charge (ENC):

$$ENC_{Series\ Noise} \propto \sqrt{k_1 \frac{C_{tot}^2}{\beta} + k_2 R_b C_{tot}^2}$$



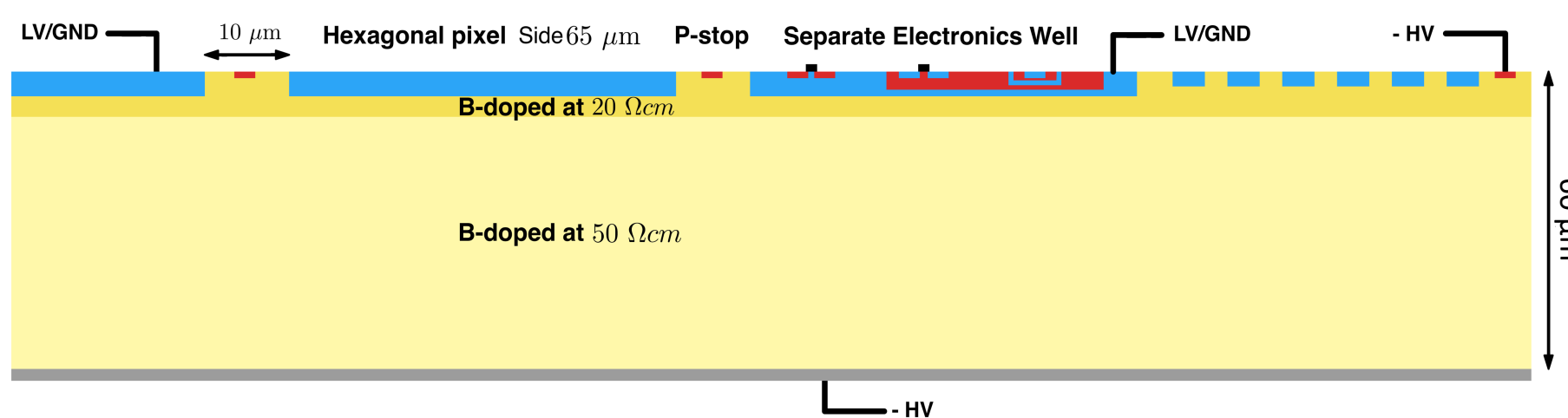
Leibniz Institute
for high
performance
microelectronics

IHP SG13G2, 130nm process.

Hexagonal pixels with large collection electrode:

- 65 μm side (100 μm pitch) + 10 μm interpixel with P-stop.
- Heavily Boron-doped (p-doped) substrate and standard low resistivity wafer

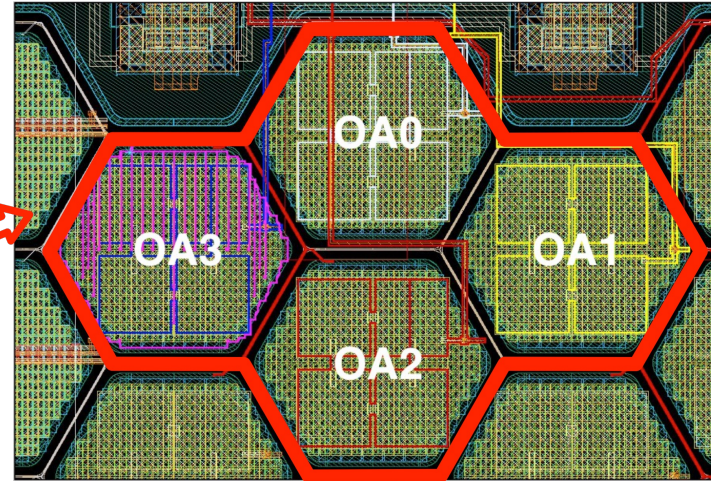
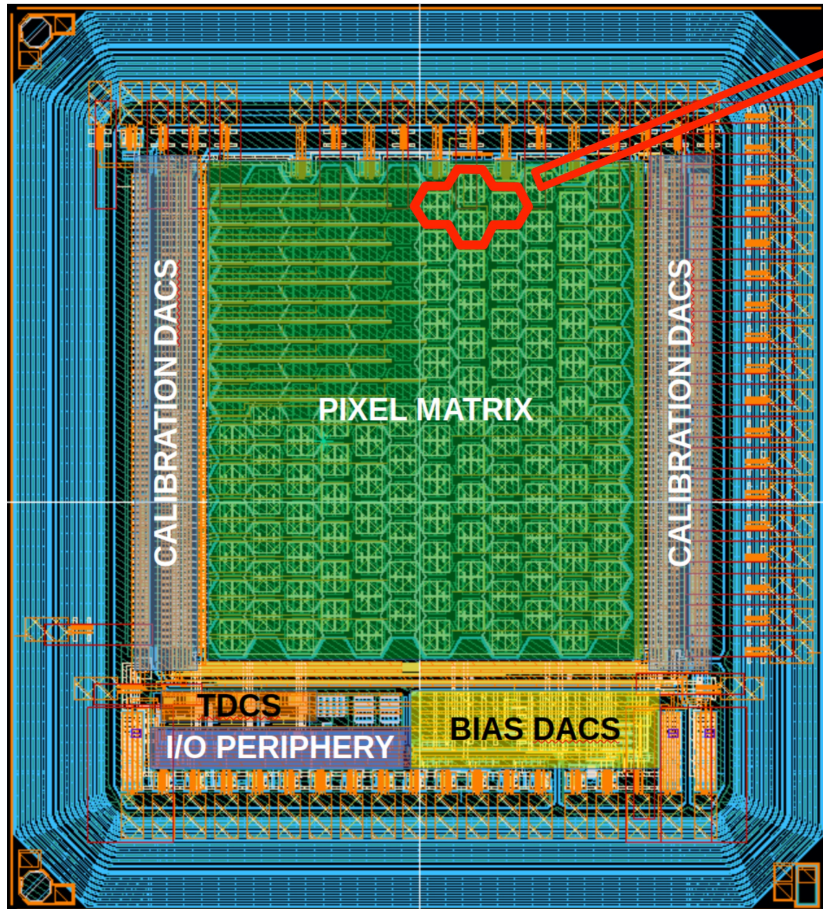
- Negative HV to substrate from backside and from top.
- Pixels and electronics in deep n-well at positive low voltage



Typical HV = -140 V:

- Depletion layer: 24 μm .
- Typical signal charge for MIP: ~ 1500 electrons.

The “ATTRACT” prototype



Four pixel with analog channels including:

- HBT pre-amplifier
- Two HBT Emitter Followers to 500Ω resistance on pad

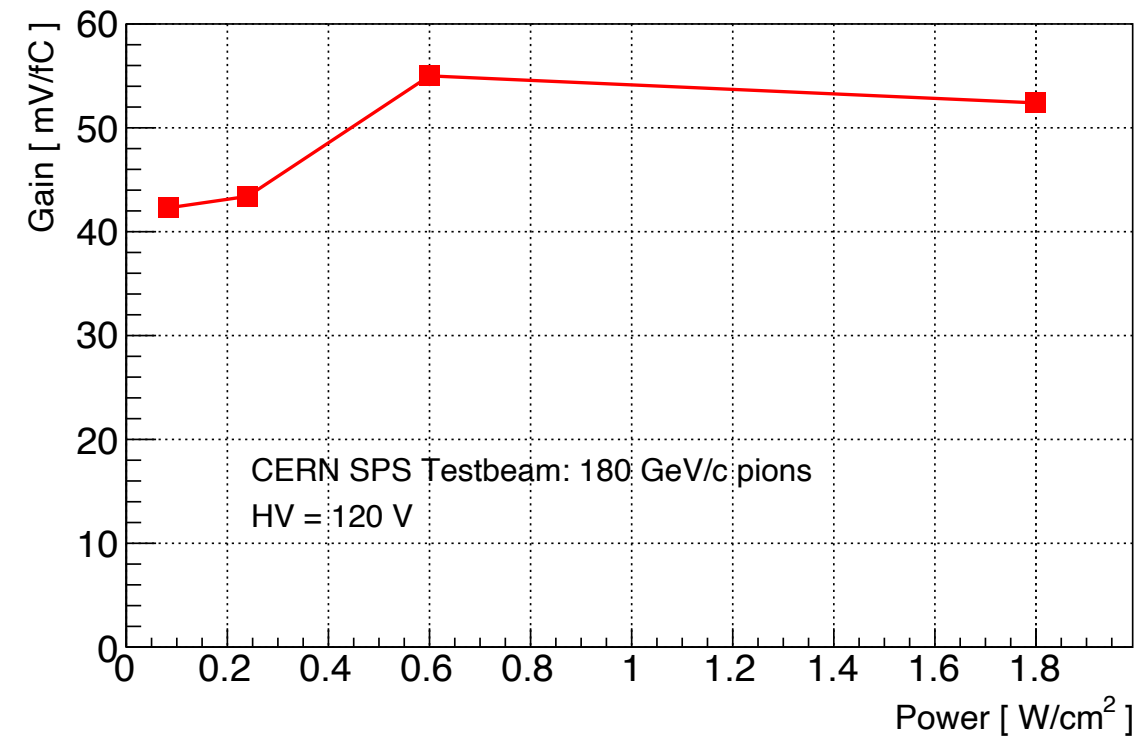
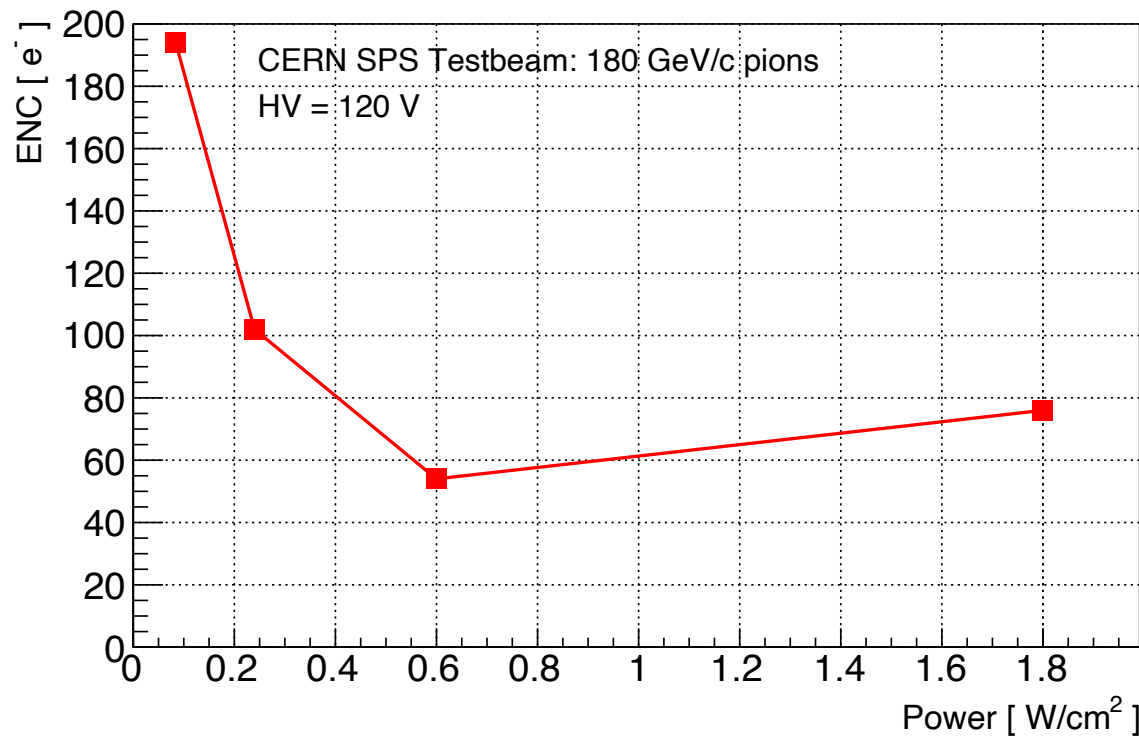
Test performed on analog channels to investigate HBT and sensor performance.

Sensor characteristics

Gain and ENC measurement of the electronic gain (pixel + pre-amplifier + driver) as a function of power consumption:

- Performed using ^{109}Cd source, two X-rays with $E_1 = 22.2$ keV and $E_2 = 24.9$ keV.
- Separate noise from electronic chain and oscilloscope following:

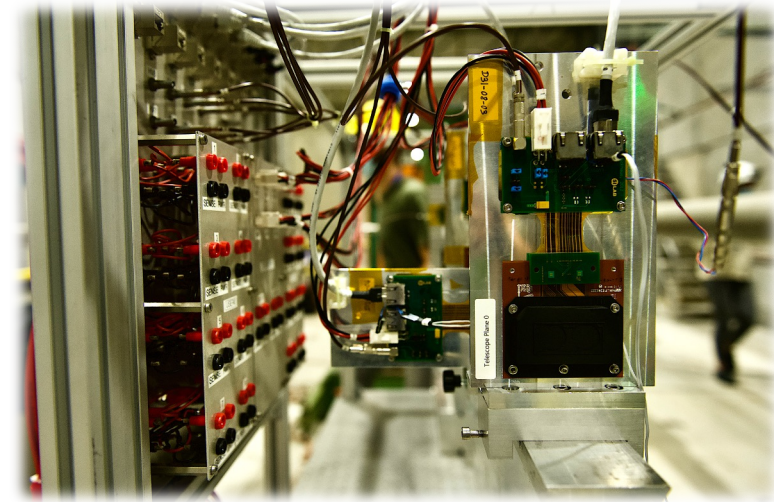
$$ENC = \frac{\sqrt{\sigma_V^2 - \sigma_{scope}^2}}{A_q}$$



Test Beam Set-Up

UNIGE FE-I4 Telescope for tracking:

- 6 planes, chip with rectangular pixels: $50\ \mu\text{m} \times 250\ \mu\text{m}$.
- Spatial resolution: $\sigma_x = 12\ \mu\text{m}$ $\sigma_y = 10\ \mu\text{m}$.

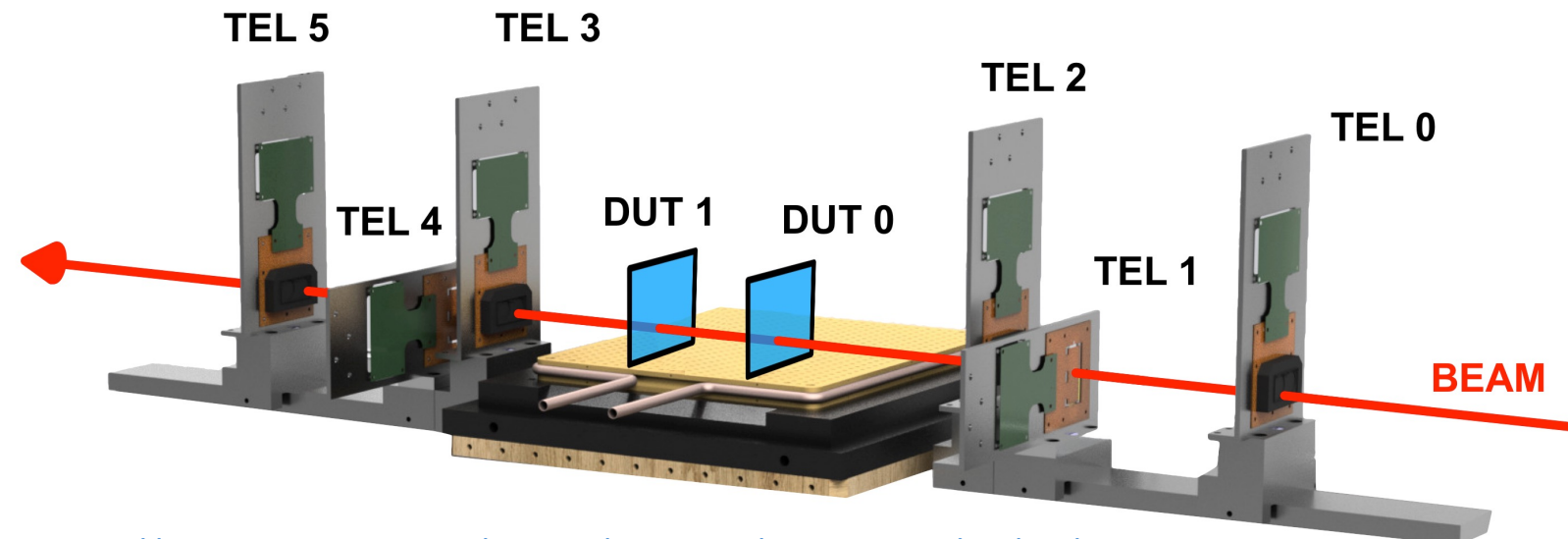


CERN SPS Test Beam with high intensity, 180 GeV/c pions.

Timing Resolution and efficiency

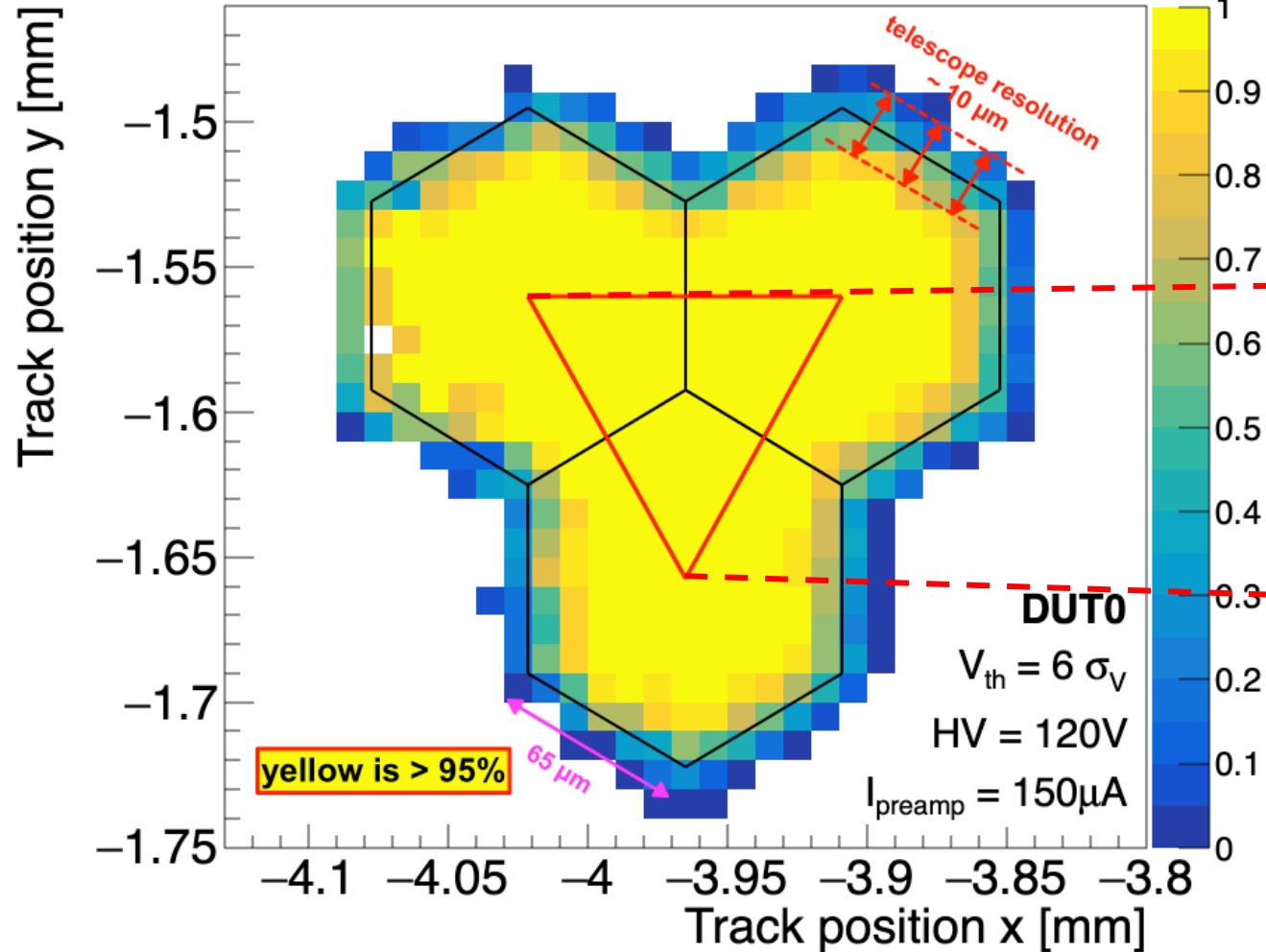
measured as a function of:

- Sensor High Voltage
- Power consumption (pre-amplifier bias current)



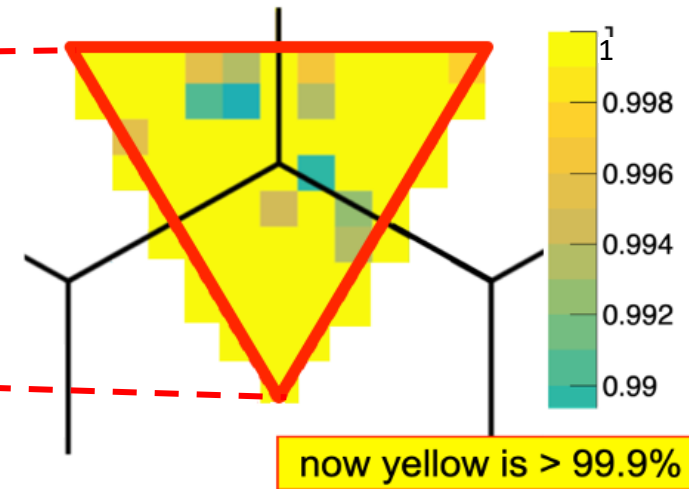
Ref: <https://iopscience.iop.org/article/10.1088/1748-0221/11/07/P07003>

Efficiency map



Getting rid of border effect from FE-I4 telescope pointing resolution :

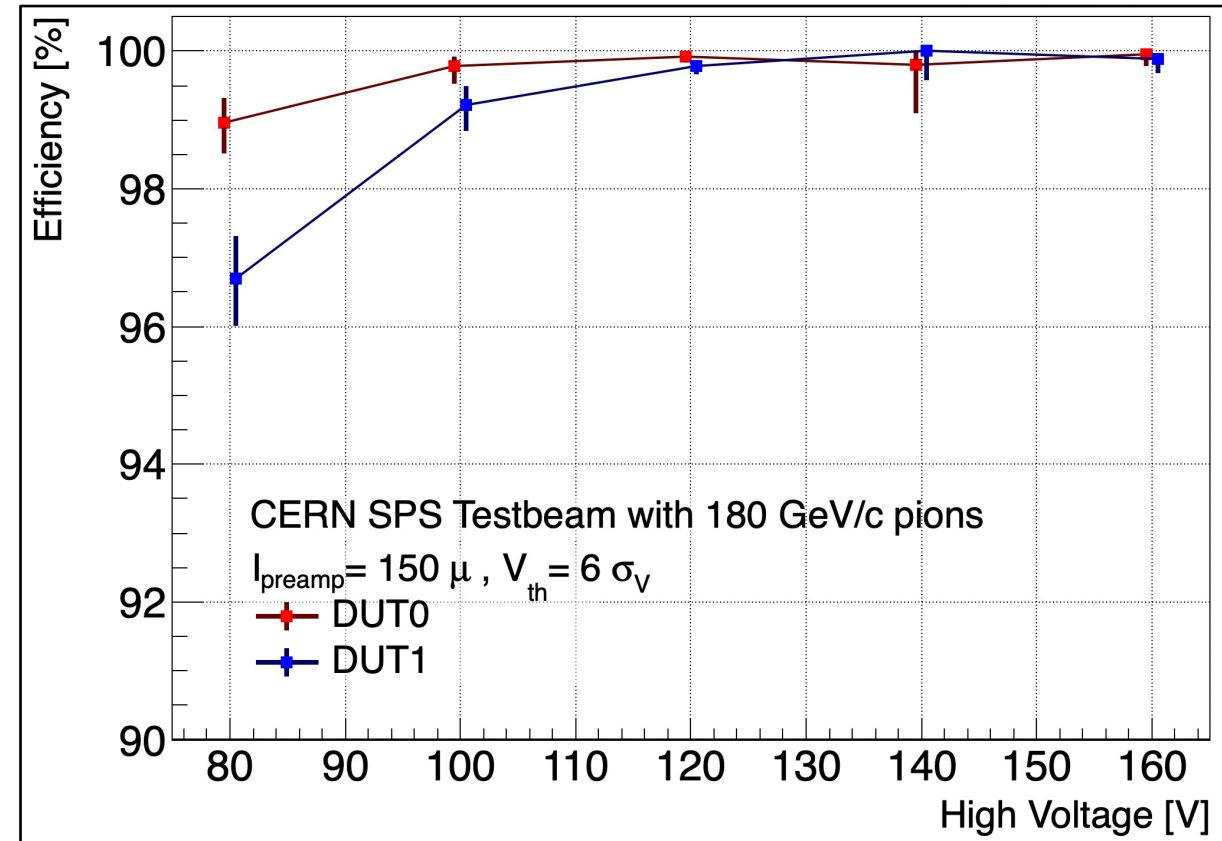
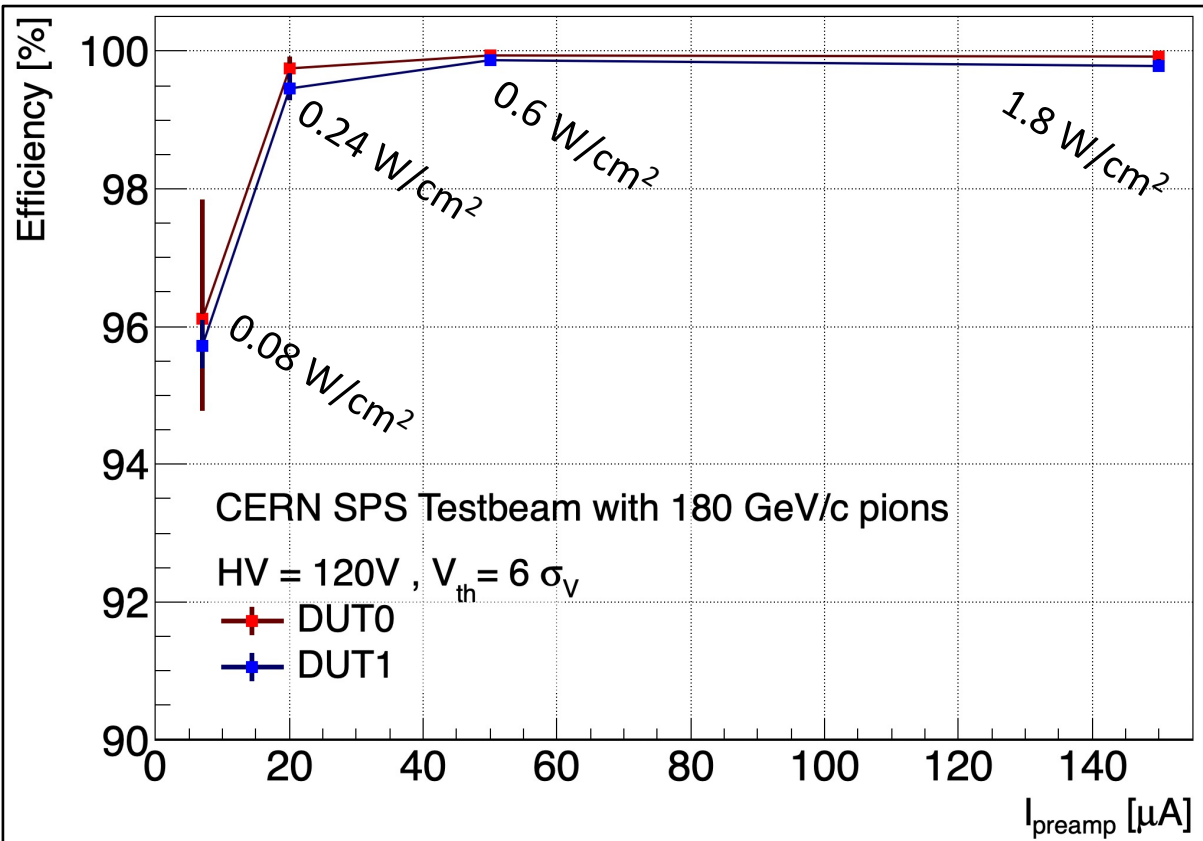
- Use bins inside area of **red triangle**, representing full pixel in right proportions.



Inside **red triangle** the efficiency is:

$$\text{Efficiency} = 99.91 \pm 0.03 - 0.08 \%$$

Efficiency scan



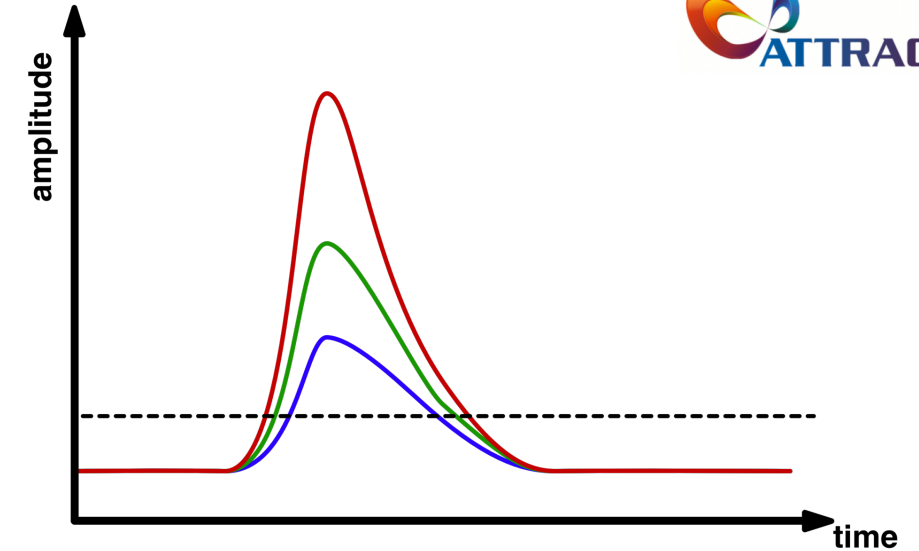
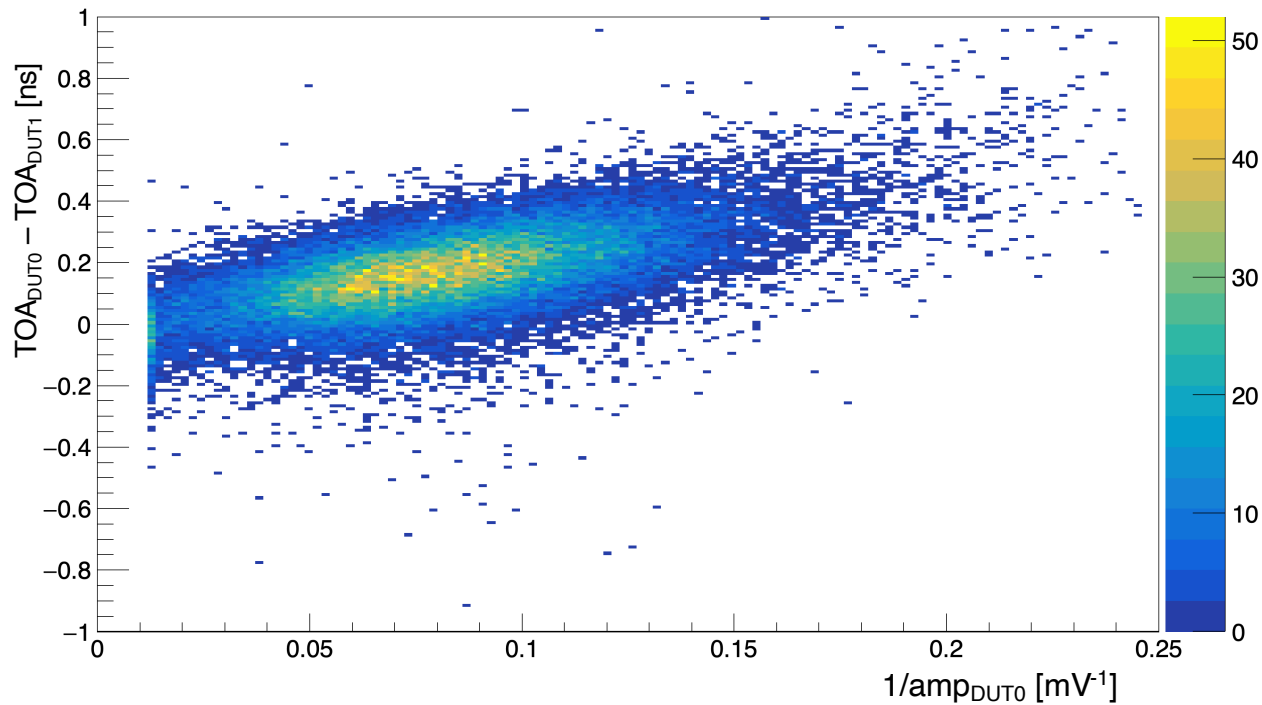
- From power consumption of 0.24 W/cm² on, efficiencies **well above 99%**.

- Efficiency “plateau” reached at 120 V.

Correcting for time walk

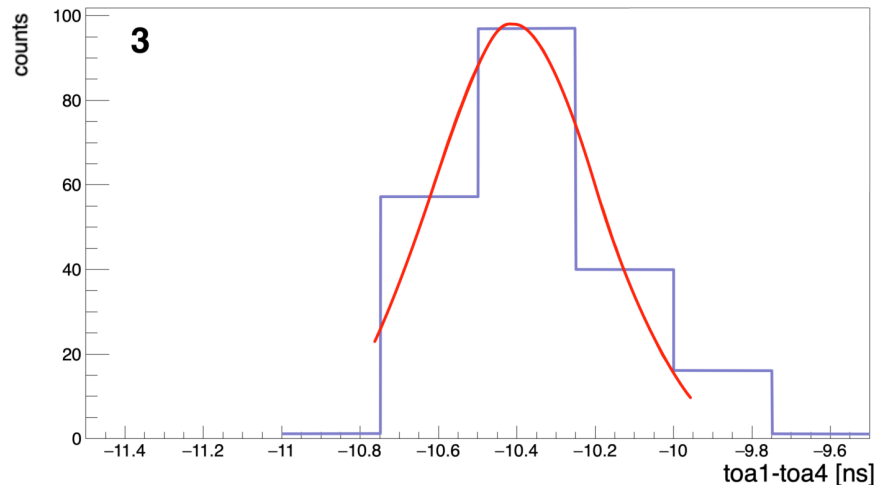
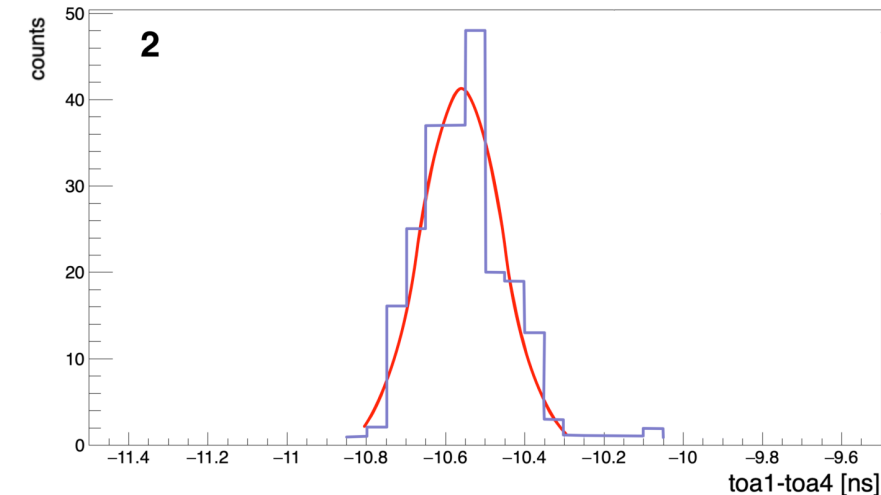
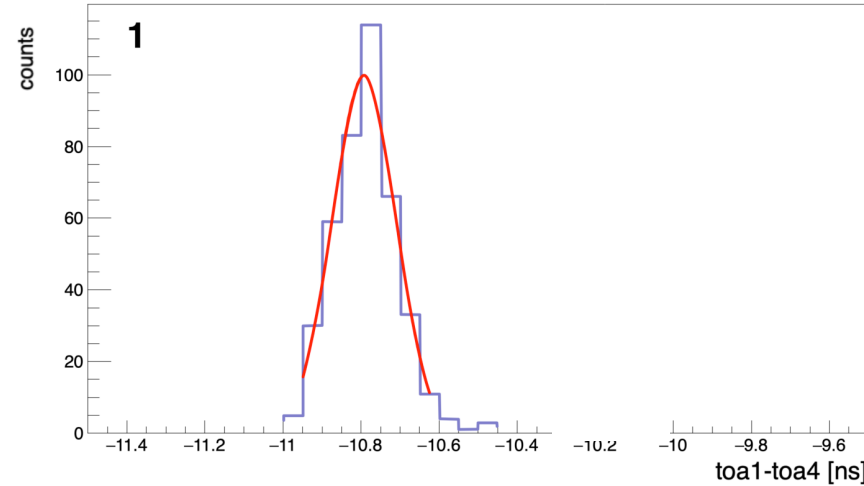
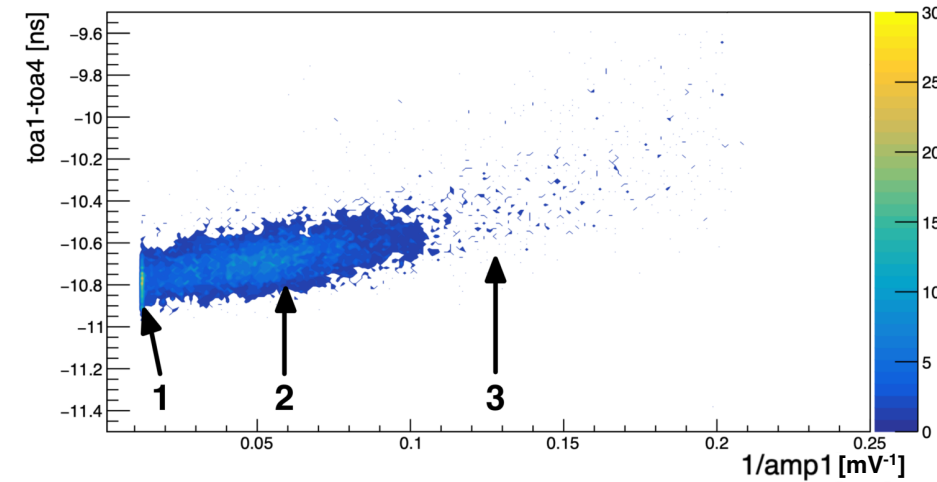
Front-end electronics gives equivalent peaking time for all signals:

- Time Walk: Time Of Arrival (TOA) different from signal to signal.
- Can be corrected with respect to amplitude of signal.



- Timing resolution measured through standard deviation of distribution of difference of TOA.
- Both DUTs corrected for time walk with respect to their own amplitude.

Correction procedure

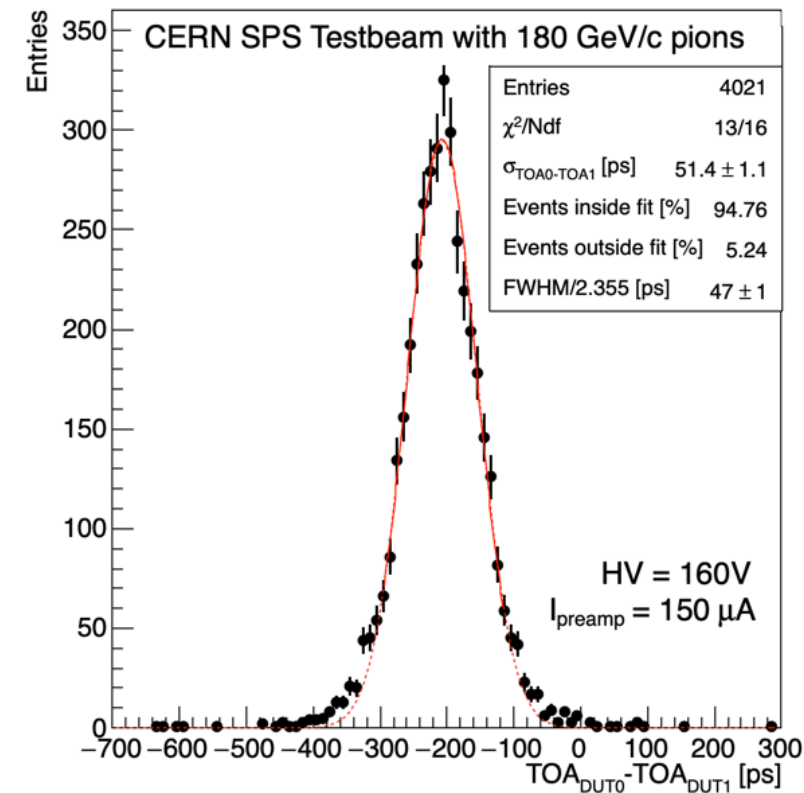
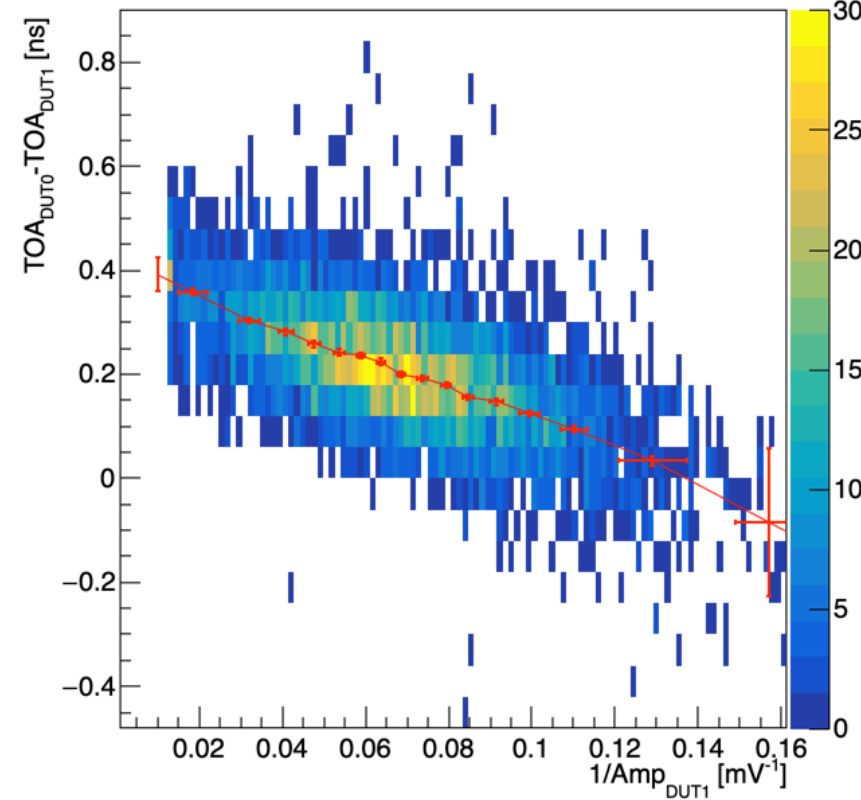
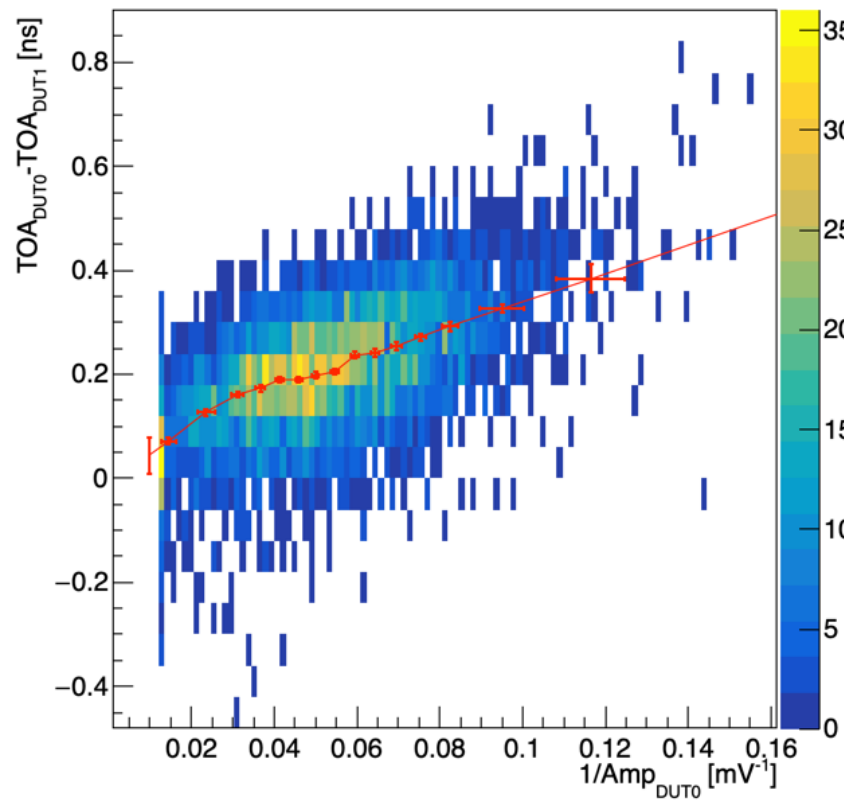


Data sampled for different values of amplitude.

Once enough events in every sample:

- Projection of the difference in TOA for the slice.
- **Gaussian fit** (since every subsample is a Gaussian) to extract the mean.
- Mean used to correct time walk

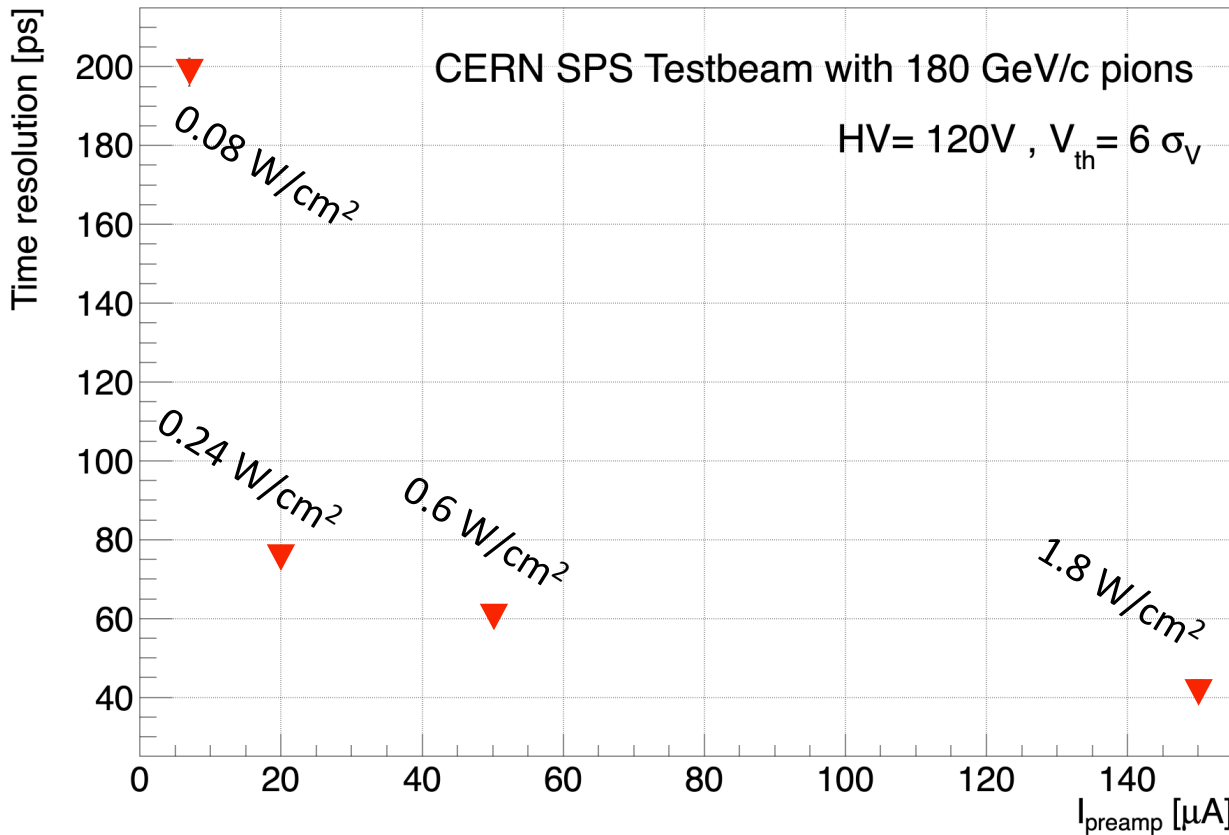
Corrected Time walk



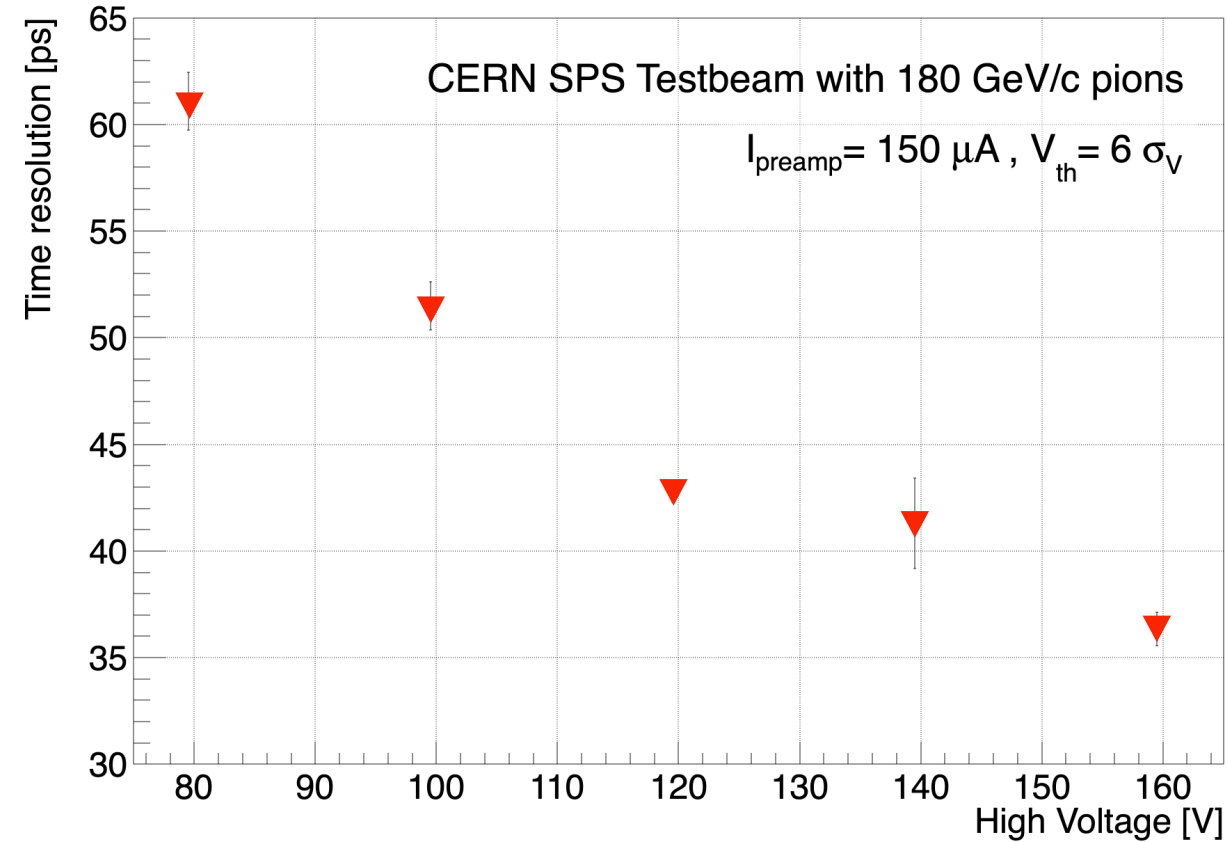
- Correction performed with respect to inverse of signal amplitude for both DUTs.

$$\sigma_t = 36.3 \pm 0.8 \text{ ps}$$

Timing Resolution



- Strong variation with power consumption as expect.
- Important degradation at 7 μA , still at the level of 200 ps.



- Time resolution varies between **60** and **36 ps** from 80V to 160V.
- Resolution at 160V is 20% better than at 120V.



Summary and Outlook



A monolithic silicon pixel sensor realized in SiGe BiCMOS 130nm process provides:

- Performance at **Power: 0.24 W/cm²** reaches **100 ps** and **99.6%** efficiency.
- Performance at **Power: 1.8 W/cm²** reaches **36 ps** and **99.9%** efficiency.

WITHOUT AVALANCHE GAIN LAYER

New sensor with integrated gain layer under study, results coming (very) soon !

Reference of paper: <https://arxiv.org/abs/2112.08999>



Thanks for your attention



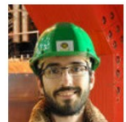
The MONOLITH Team:



Giuseppe Iacobucci
• project P.I.
• System design



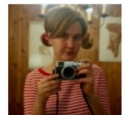
Didier Ferrere
• System integration
• Laboratory test



Pierpaolo Valerio
• Lead chip design
• Digital electronics



Mateus Vicente
• System integration
• Laboratory test



Yana Gurinskaya
• Radiation tolerance
• Laboratory test



Stefano Zambito
• Laboratory test



Lorenzo Paolozzi
• Sensor design
• Analog electronics



Sergio Gonzalez-Sevilla
• System integration
• Laboratory test



Magdalena Munker
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• Laboratory test



Roberto Cardella
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Fulvio Martinelli
• Chip design



Yannick Favre
• Board design
• RO system



Stéphane Débieux
• Board design
• RO system



Théo Moretti
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Antonio Picardi
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KIT



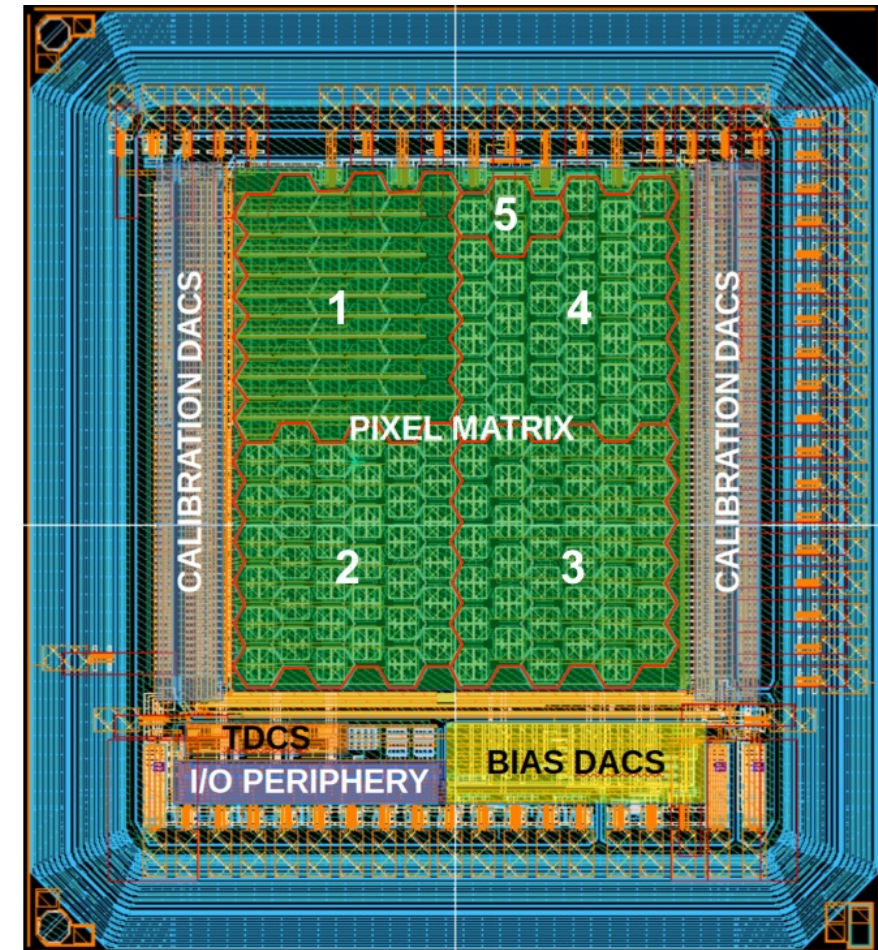
Bernd Heinemann
IHP Mikroelektronik



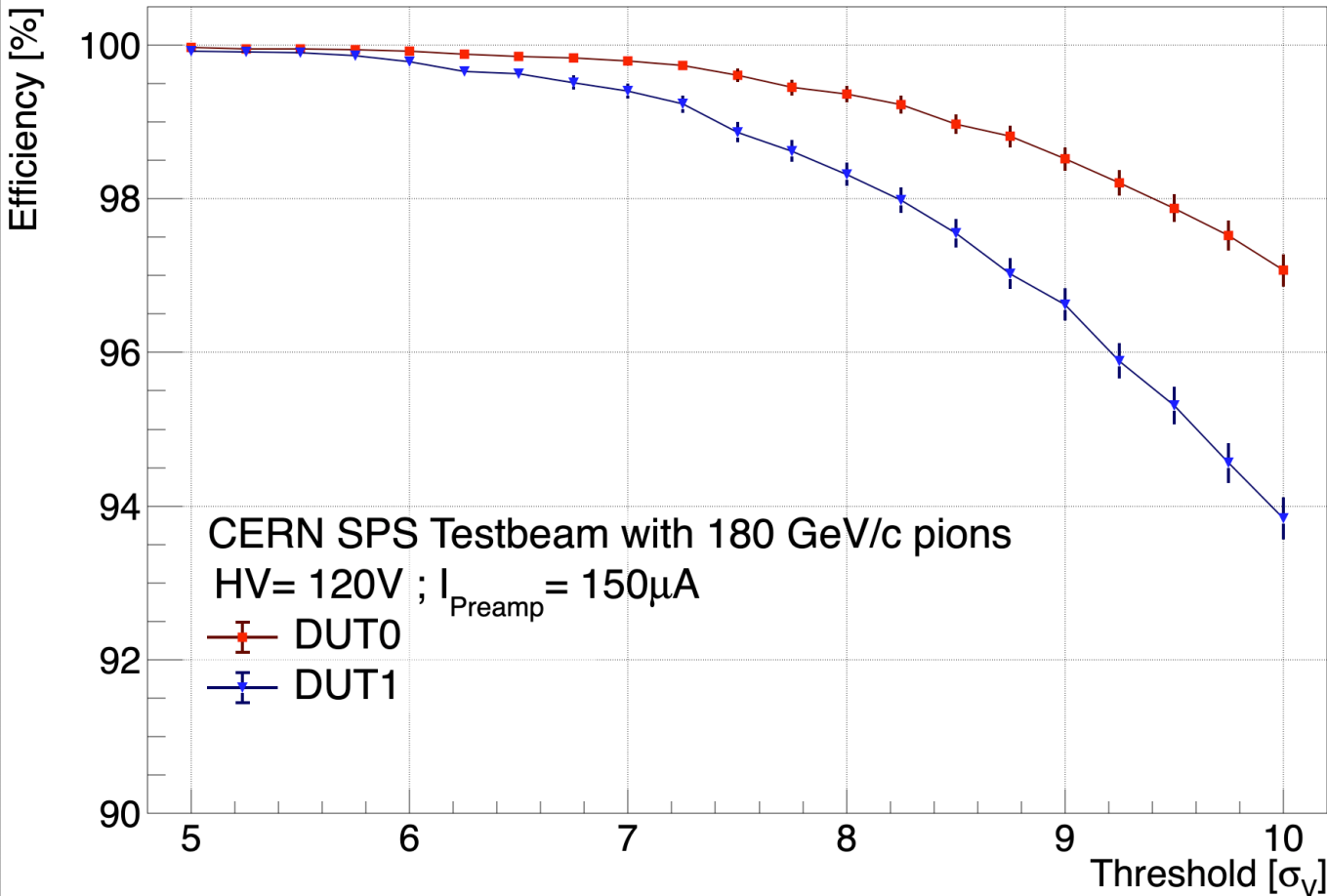
Sensor design

ASIC prototype with 12x12, 65 μ m side hexagonal pixels with 80fF capacitance come in different “flavors”:

1. Active pixel
 - Front end in pixel
 - HBT preamplifier + driver (in pixel) + CMOS discriminator (outside pixel)
2. PET-project version:
 - HBT preamplifier + CMOS discriminator
3. Limiting amplifier:
 - HBT preamplifier + HBT limiting amplifier
4. Double Threshold
 - HBT preamplifier + two CMOS discriminators



Efficiency Threshold scan



- Both DUT reach efficiency plateau at **6 standard deviation** from noise (σ_v), well above 99%.
- Clear difference in performance between the two sensors.
- Trend can be explained by the **difference in ENC**. (76 ± 1 electrons for **DUT 0** and 82 ± 1 electrons for **DUT 1**)